

FOR: BE SEMICONDUCTOR INDUSTRIES N.V.
Ratio 6
6921 RW Duiven, The Netherlands

PRESS RELEASE

BE Semiconductor Industries Announces Strengthening of Management Team

Duiven, the Netherlands, December 1, 2010, BE Semiconductor Industries N.V. ("the Company" or "Besì") (Euronext: BESI), a leading manufacturer of assembly equipment for the semiconductor industry, today announced the hiring of Berthold Butzmann as Chief Operating Officer and Guido Slump as Senior Vice President-Packaging Products.

Mr Butzmann (49) will be designated Chief Operating Officer effective April 2011 and will be based at the Company's facilities in Kuala Lumpur, Malaysia. He will be responsible for the management and oversight of Besì's global production activities, supply chain network and spare parts. Mr Butzmann has over 20 years of experience in the semiconductor equipment and machine building industries with a specialization in European and Asian manufacturing operations, supply chain management and the deployment of ERP and production efficiency systems. Prior to joining Besì, he worked for the past 10 years in executive capacities at Multitest Elektronische Systeme GmbH (a division of Dover Corporation) most recently as Vice President Operations in its Handling and Socket division.

Mr Slump (53) will be designated Senior Vice President-Packaging Products effective December 2010. He will be responsible for the management of Besì's range of Fico packaging equipment products based in Duiven, the Netherlands. Mr Slump has 27 years of experience in capital goods manufacturing, development and sales. Prior to joining Besì, he worked in executive management and sales capacities for European manufacturing companies such as Antonius Vessel Heads, Vege Engines, Tebel Pneumatics, FIB Apparatenbouw, and Stork X-cel as well as interim executive management positions for Kappa Packaging, Ford Motor Company and Stork Aerostructures. He succeeds Mr Hans Wunderl who will continue as an advisor to the Company focused on strategic projects of importance to Besì's systems business.

In addition, the Company announced the formation of an executive committee of Besì's management team to oversee its global operations. Members of the executive committee will include Mr Richard W. Blickman, Chief Executive Officer, Mr Berthold Butzmann, Chief Operating Officer, Mr Peter Wiedner, Senior Vice President-Die Attach, Mr Cor te Hennepe, Senior Vice President-Finance and Mr J.K. Park, Senior Vice President Sales & Customer Support APac.

About Besì

Besì is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries. The Company develops leading edge assembly processes and equipment for leadframe, array connect and wafer level packaging applications in a wide range of end-user markets including electronics, computer, automotive, industrial, RFID, LED and solar energy. Customers are primarily leading semiconductor manufacturers, assembly subcontractors and electronics and industrial companies. Besì's ordinary shares are listed on NYSE Euronext Amsterdam (symbol: BESI) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at www.besi.com.

Contacts:

Richard W. Blickman
President & CEO
Tel. (31) 26 319 4500
investor.relations@besi.com

Cor te Hennepe
Senior Vice President Finance
Tel. (31) 26 319 4500
investor.relations@besi.com

European IR contacts:

Uneke Dekkers/Frank Jansen
Citigate First Financial
Tel. (31) 20 575 4021/24